

L Number	Hits	Search Text	DB	Time stamp
1	14	(156/\$.ccls.) and (compression\$) and (die near2 bond\$) and (damage)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/23 12:30
-	208	(156/102).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 11:25
-	456	(156/298).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 20:33
-	1064	(156/64).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 18:37
-	332	(156/358).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:23
-	194	(156/360).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:35
-	263	((156/367) or (156/368)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:46
-	693	((156/378) or (156/379)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:47
-	561	(156/299).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 11:57
-	1856	(29/832).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 18:43
-	6	((29/832).CCLS.) and (sensor\$ near3 optical) and (solder) and (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 13:55
-	0	((29/832).CCLS.) and (sensor\$ near3 optical) and(anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 19:44

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-	0	((29/832).CCLS.) and (sensor\$ near3 optical) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 12:16
-	0	((29/832).CCLS.) and (sensor\$ near3 assembly) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 18:44
-	40	((29/832).CCLS.) and (sensor\$) and (solder) and (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 14:56
-	2893	((29/739) or (29/740)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 18:58
-	0	((29/739) or (29/740)).CCLS.) and (sensor\$ near3 assembly) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/23 12:22
-	5	((29/739) or (29/740)).CCLS.) and (sensor\$) and (anisotropic\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 18:48
-	901	(438/118).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 18:59
-	5	((438/118).CCLS.) and (sensor\$ near3 assembly)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 19:02
-	109	(156/\$.ccls.) and (indium or germanium) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 20:02
-	3	(156/\$.ccls.) and (germanium near3 solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 20:06